

Applications

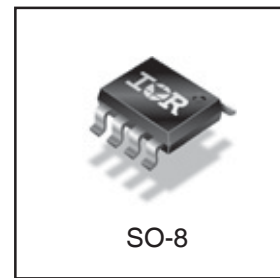
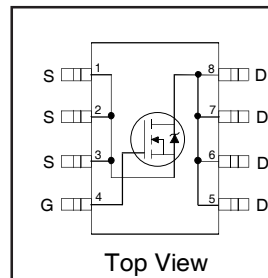
- High Frequency DC-DC Isolated Converters with Synchronous Rectification for Telecom and Industrial use
- High Frequency Buck Converters for Computer Processor Power
- Lead-Free

HEXFET® Power MOSFET

V_{DSS}	R_{DS(on)} max	I_D
30V	8mΩ	14A

Benefits

- Ultra-Low Gate Impedance
- Very Low R_{DS(on)} at 4.5V V_{GS}
- Fully Characterized Avalanche Voltage and Current



Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-to-Source Voltage	± 12	V
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V	14	A
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V	11	
I _{DM}	Pulsed Drain Current ^①	110	
P _D @ T _A = 25°C	Maximum Power Dissipation	2.5	W
P _D @ T _A = 70°C	Maximum Power Dissipation	1.6	W
	Linear Derating Factor	0.02	mW/°C
T _J , T _{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
R _{θJL}	Junction-to-Drain Lead ^⑤	—	20	°C/W
R _{θJA}	Junction-to-Ambient ^{④⑤}	—	50	

Notes ^① through ^⑤ are on page 8
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IRF7463PbF

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

International
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	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.029	—	V/°C	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	6.0	8.0	mΩ	$V_{GS} = 10V, I_D = 14A$ ③
		—	7.0	9.5		$V_{GS} = 4.5V, I_D = 11A$ ③
		—	10.5	20		$V_{GS} = 2.7V, I_D = 7.0A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	0.6	—	2.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 24V, V_{GS} = 0V$
		—	—	100		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	200	nA	$V_{GS} = 12V$
	Gate-to-Source Reverse Leakage	—	—	-200		$V_{GS} = -12V$

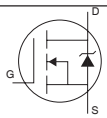
Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

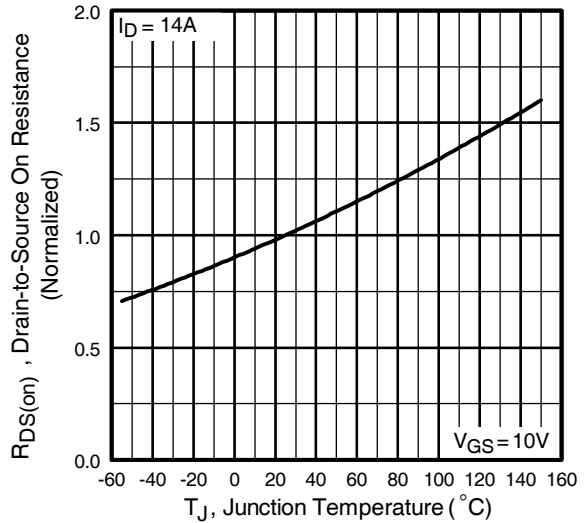
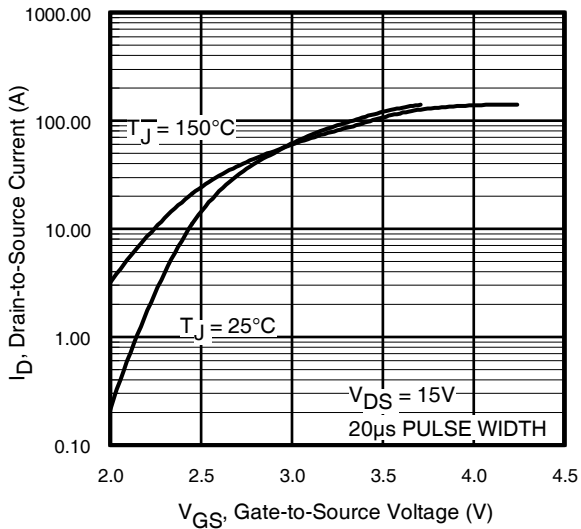
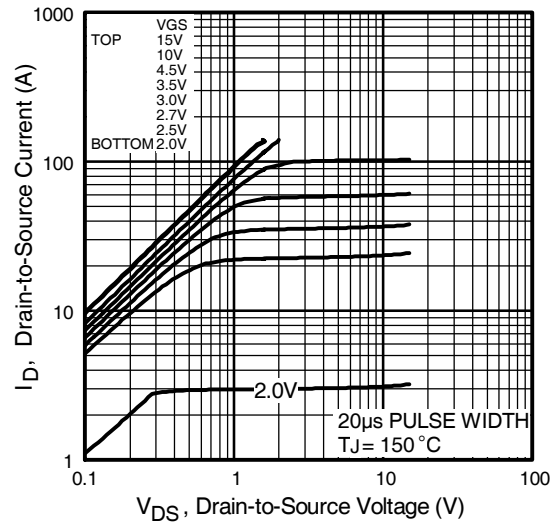
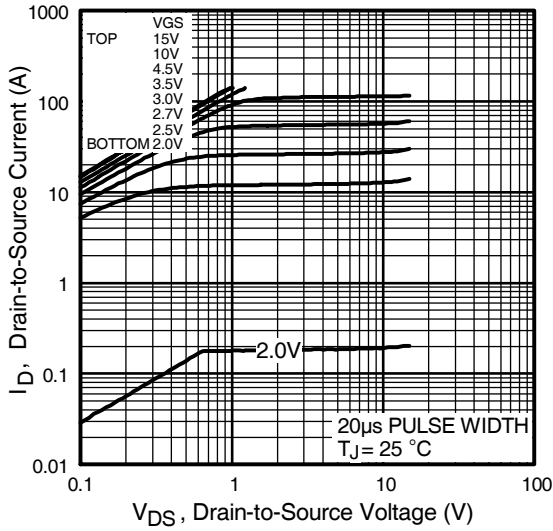
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	41	—	—	S	$V_{DS} = 24V, I_D = 11A$
Q_g	Total Gate Charge	—	34	51	nC	$I_D = 11A$
Q_{gs}	Gate-to-Source Charge	—	7.6	11.4		$V_{DS} = 15V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	12	18		$V_{GS} = 4.5V$ ③
Q_{oss}	Output Gate Charge	—	21	32		$V_{GS} = 0V, V_{DS} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	16	—	ns	$V_{DD} = 15V$
t_r	Rise Time	—	138	—		$I_D = 11A$
$t_{d(off)}$	Turn-Off Delay Time	—	28	—		$R_G = 1.8\Omega$
t_f	Fall Time	—	6.5	—		$V_{GS} = 4.5V$ ③
C_{iss}	Input Capacitance	—	3150	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	1070	—		$V_{DS} = 15V$
C_{rss}	Reverse Transfer Capacitance	—	180	—		$f = 1.0\text{MHz}$

Avalanche Characteristics

Symbol	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	320	mJ
I_{AR}	Avalanche Current①	—	14	A

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	110		
V_{SD}	Diode Forward Voltage	—	0.52	1.3	V	$T_J = 25^\circ\text{C}, I_S = 11A, V_{GS} = 0V$ ③
		—	0.44	—		$T_J = 125^\circ\text{C}, I_S = 11A, V_{GS} = 0V$ ③
t_{rr}	Reverse Recovery Time	—	45	70	ns	$T_J = 25^\circ\text{C}, I_F = 11A, V_R = 15V$
Q_{rr}	Reverse Recovery Charge	—	65	100	nC	$di/dt = 100A/\mu s$ ③
t_{rr}	Reverse Recovery Time	—	50	75	ns	$T_J = 125^\circ\text{C}, I_F = 11A, V_R = 15V$
Q_{rr}	Reverse Recovery Charge	—	80	120	nC	$di/dt = 100A/\mu s$ ③



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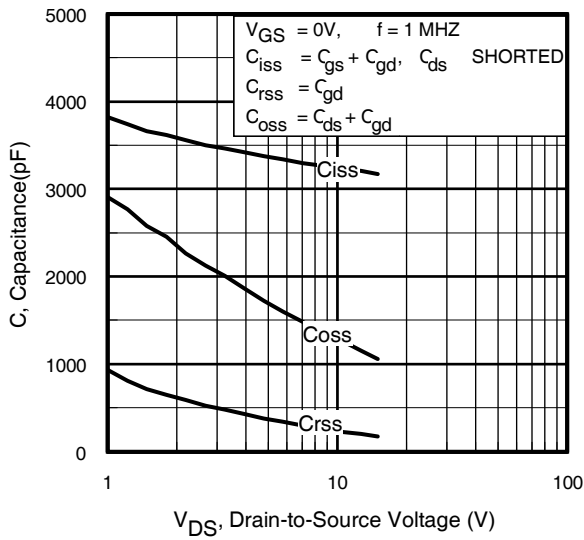


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

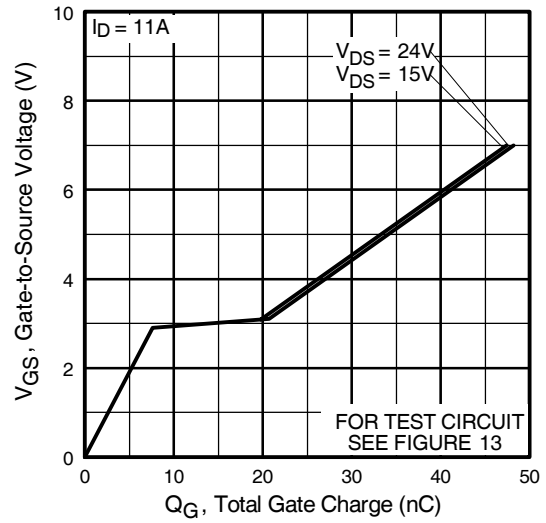


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

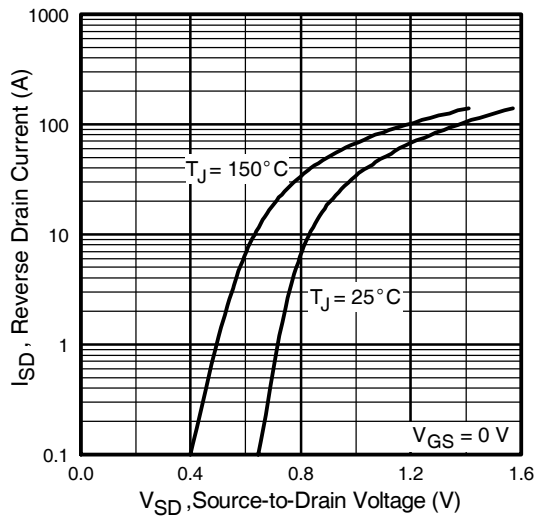


Fig 7. Typical Source-Drain Diode Forward Voltage

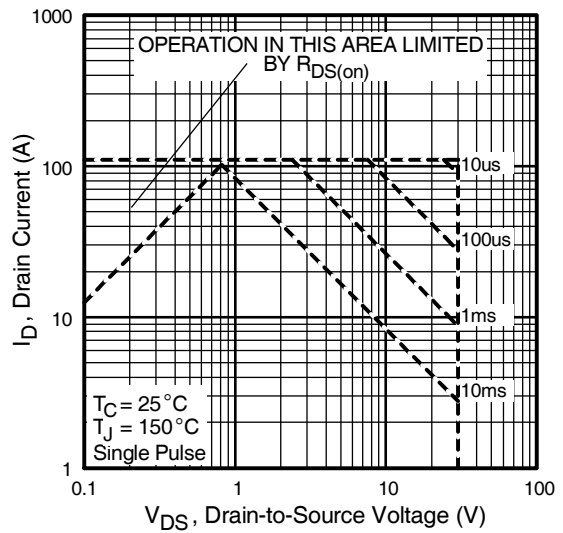


Fig 8. Maximum Safe Operating Area

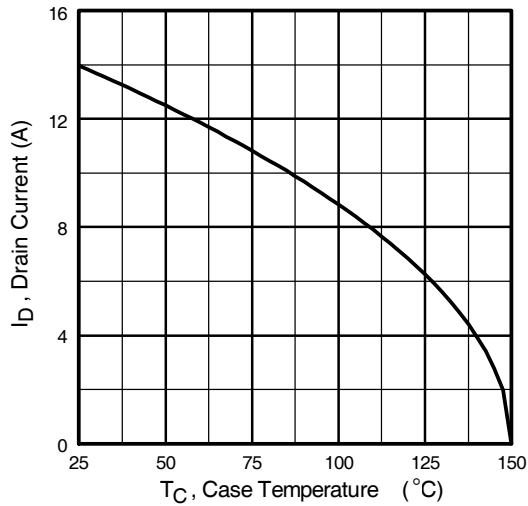


Fig 9. Maximum Drain Current Vs. Case Temperature

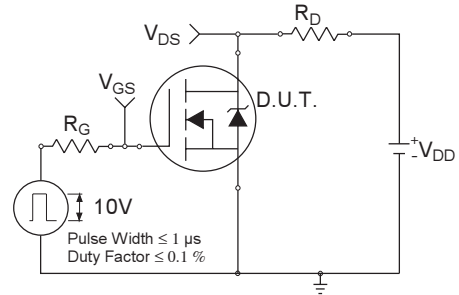


Fig 10a. Switching Time Test Circuit

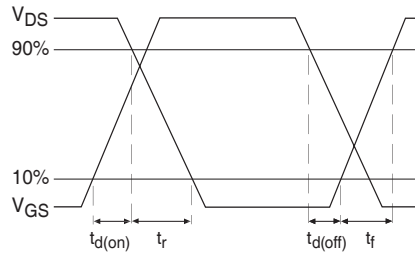


Fig 10b. Switching Time Waveforms

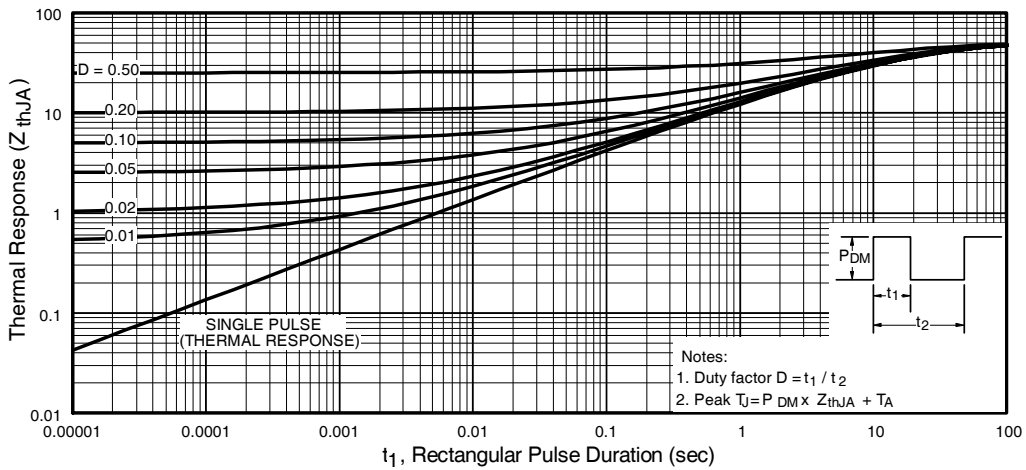


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

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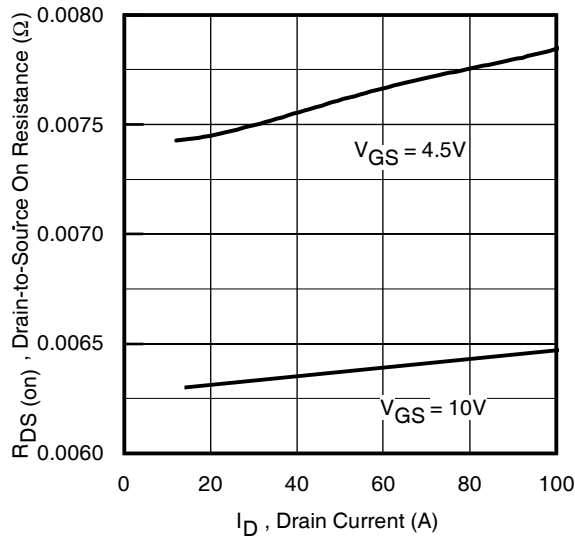


Fig 12. On-Resistance Vs. Drain Current

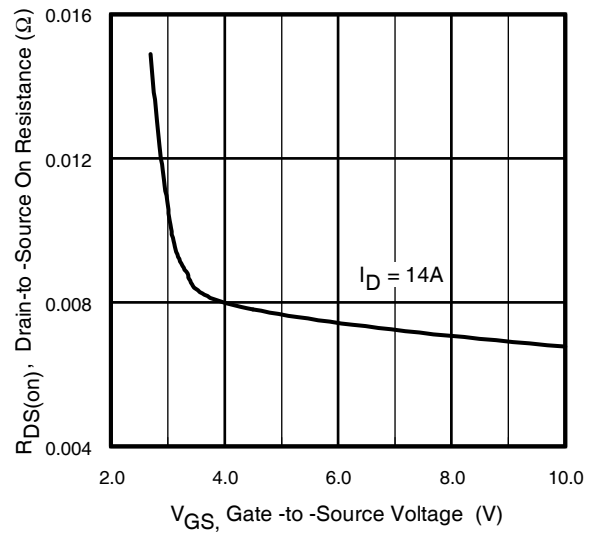


Fig 13. On-Resistance Vs. Gate Voltage

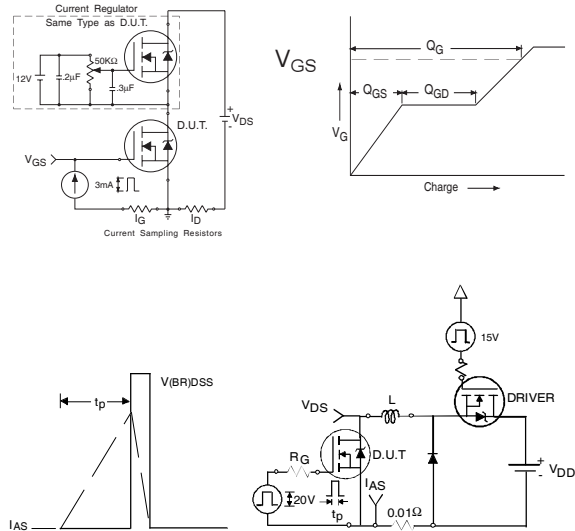


Fig 15a&b. Unclamped Inductive Test circuit and Waveforms

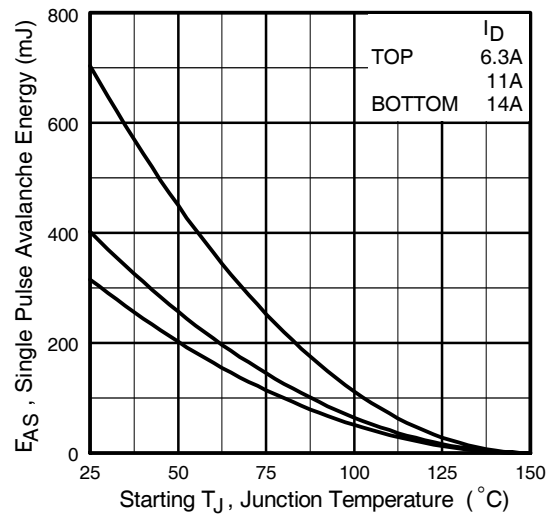
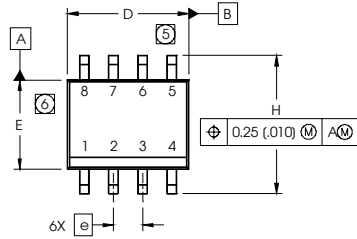


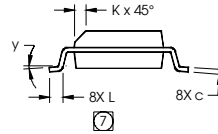
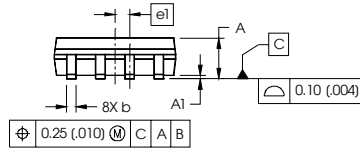
Fig 15c. Maximum Avalanche Energy Vs. Drain Current

SO-8 Package Outline

Dimensions are shown in millimeters (inches)



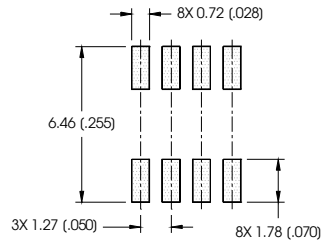
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



NOTES:

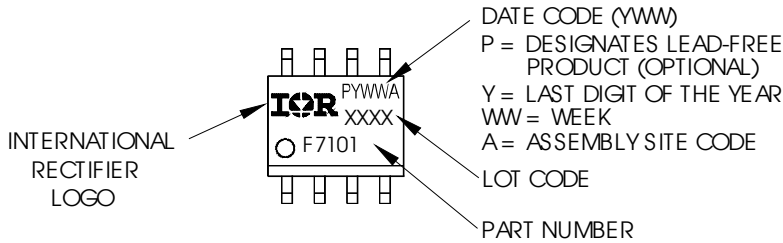
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
- ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT

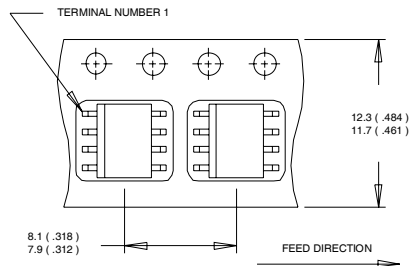


SO-8 Part Marking Information (Lead-Free)

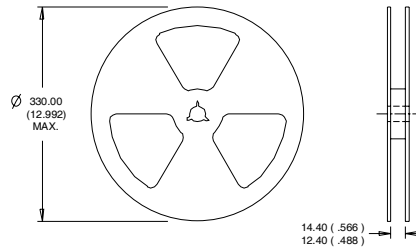
EXAMPLE: THIS IS AN IRF7101 (MOSFET)



SO-8 Tape and Reel



- NOTES:
 1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
 1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^\circ\text{C}$, $L = 3.3\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = 14\text{A}$.
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board, $t < 10$ sec
- ⑤ R_θ is measured at T_J approximately 90°C

Data and specifications subject to change without notice.
 This product has been designed and qualified for the Consumer market.
 Qualification Standards can be found on IR's Web site.